

TCA9849 Ultra Low-Voltage 4-Channel 1Mhz Capable I²C Multiplexer

1 Features

- 1-to-4 Bidirectional translating multiplexer with ultra low voltage translation down to 0.65V
- I²C Bus and SMBus compatible
- Active-low reset input
- 2 address pins, allowing up to 16 TCA9849 devices on the I²C bus
- Channel selection through an I²C Bus, in any combination
- Power up with all switch channels deselected
- Low R_{ON} switches
- Allows voltage-level translation between 0.65V, 0.8, 1.2V, 1.8V, 2.5V, and 3.3V
- No glitch on power up
- Supports hot insertion
- Low standby current
- Operating power-supply V_{DD2} voltage range of 1.65V to 3.6V
- Operating power-supply voltage V_{DD1} range of 0.65V to 3.6V
- 3.6V Tolerant inputs
- 0 to 1MHz Clock frequency
- Latch-up performance exceeds 100mA Per JESD 78, class II
- ESD Protection exceeds JESD 22
 - ±2000V Human-body model (A114A)
 - ±500V Charged-device model (C101)

2 Applications

- Servers
- Routers (telecom switching equipment)
- [Factory Automation](#)
- Products with I²C target address conflicts (such as multiple, identical temperature sensors)

3 Description

The TCA9849 device is an 4-channel, bidirectional translating multiplexer that can be controlled through the I²C bus. The SCL/SDA upstream pair fans out to four downstream pairs, or channels. Any individual SCn/SDn channel or combination of channels can be selected, determined by the contents of the programmable control register. These downstream channels can be used to resolve I²C target address conflicts. For example, if four identical digital temperature sensors are needed in the application, one sensor can be connected at each channel: 0-3.

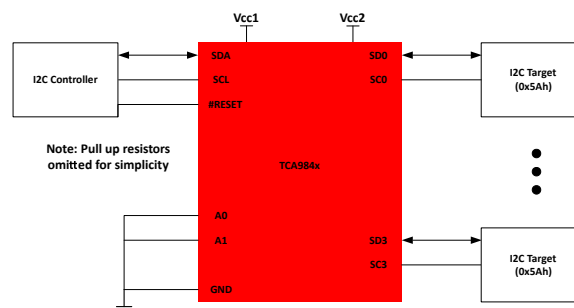
The system controller can reset the TCA9849 in the event of a time-out, or other improper operation by asserting a low in the RESET input. Similarly, the power-on reset deselects all channels and initializes the I²C/SMBus state machine. Asserting RESET causes the same reset and initialization to occur without powering down the part. This allows recovery if one of the downstream I²C buses get stuck in a low state.

The pass gates of the switches are constructed so that VDD1/VDD2 pins can be used to limit the maximum high voltage, which is passed by the TCA9849. Limiting the maximum high voltage allows the use of different bus voltages on each pair, so that 0.65V, 0.8V, 1.2V, or 1.8V parts can communicate with 3.3V parts, without any additional protection. External pullup resistors pull the bus up to the desired voltage level for each channel. All I/O pins are 3.6V tolerant.

Packaging Information

PART NUMBER	PACKAGE (1)	PACKAGE SIZE (2)
TCA9849	PW (TSSOP, 16)	5.00mm × 4.40mm
	RUM (WQFN, 16)	4.00mm × 4.00mm

- (1) For all available packages, see the orderable addendum at the end of the data sheet.
- (2) The package size (length x width) is a nominal value and includes pins, where applicable



Simplified Application Diagram



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4 Pin Configuration and Functions

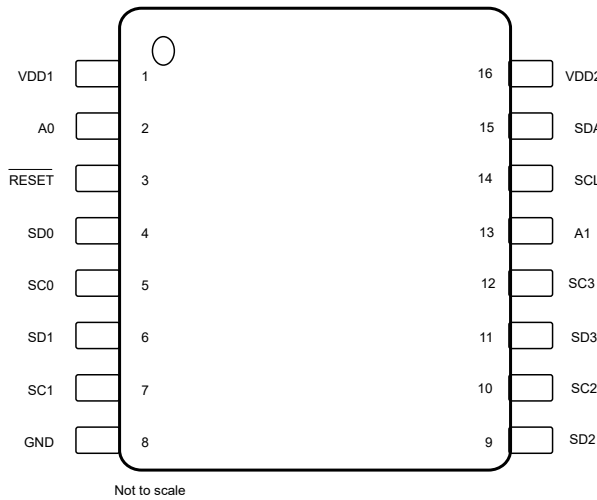


Figure 4-1. PW Package, 16-Pin TSSOP (Top View)

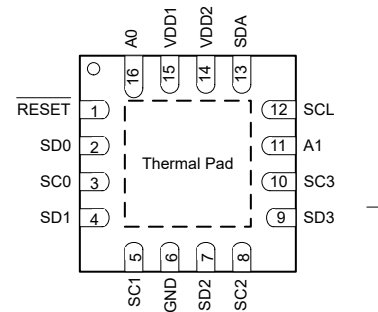


Figure 4-2. RUM Package, 16-Pin WQFN (Top View)

Table 4-1. Pin Functions

NAME	PIN		TYPE ⁽¹⁾	DESCRIPTION
	TSSOP (PW)	WQFN (RUM)		
A0	2	16	I	Address input 0. Connect directly to V _{DD2} or ground
A1	13	11	I	Address input 1. Connect directly to V _{DD2} or ground
VDD1	1	15	P	Logic Level Power Supply(VCC)
VDD2	16	14	P	Core Logic Power Supply(VCC)
RESET	3	1	I	Active-low reset input. Connect to V _{DD2} or V _{DPUM} ⁽²⁾ through a pull-up resistor, if not used
SD0	4	2	I/O	Serial data 0. Connect to V _{DPU0} ⁽²⁾ through a pull-up resistor
SC0	5	3	I/O	Serial clock 0. Connect to V _{DPU0} ⁽²⁾ through a pull-up resistor
SD1	6	4	I/O	Serial data 1. Connect to V _{DPU1} ⁽²⁾ through a pull-up resistor
SC1	7	5	I/O	Serial clock 1. Connect to V _{DPU1} ⁽²⁾ through a pull-up resistor
SD2	9	7	I/O	Serial data 2. Connect to V _{DPU2} ⁽²⁾ through a pull-up resistor
SC2	10	8	I/O	Serial clock 2. Connect to V _{DPU2} ⁽²⁾ through a pull-up resistor
SD3	11	9	I/O	Serial data 3. Connect to V _{DPU3} ⁽²⁾ through a pull-up resistor
SC3	12	10	I/O	Serial clock 3. Connect to V _{DPU3} ⁽²⁾ through a pull-up resistor
SCL	14	12	I/O	Serial clock bus. Connect to V _{DPUM} ⁽²⁾ through a pull-up resistor
SDA	15	13	I/O	Serial data bus. Connect to V _{DPUM} ⁽²⁾ through a pull-up resistor
GND	8	6	-	Supply Ground

(1) I = input, O = output, P = power

(2) V_{DPUX} is the pull-up reference voltage for the associated data line. V_{DPUM} is the controller I²C reference voltage and V_{DPU0}-V_{DPU3} are the target channel reference voltages.

5 Specifications

5.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted) ⁽¹⁾

		MIN	MAX	UNIT
V _{CC}	Supply voltage	−0.5	4	V
V _I	Input voltage ⁽²⁾	−0.5	4	V
I _I	Input current	−20	20	mA
I _O	Output current	−25	25	mA
I _{CC}	Supply current	−100	100	mA
T _{amb}	Ambient Temperature	−40	125	°C
T _{stg}	Storage temperature	−65	150	°C

- (1) Operation outside the Absolute Maximum Ratings may cause permanent device damage. Absolute Maximum Ratings do not imply functional operation of the device at these or any other conditions beyond those listed under Recommended Operating Conditions. If used outside the Recommended Operating Conditions but within the Absolute Maximum Ratings, the device may not be fully functional, and this may affect device reliability, functionality, performance, and shorten the device lifetime.
- (2) The input negative-voltage and output voltage ratings can be exceeded if the input and output current ratings are observed.

5.2 ESD Ratings

			VALUE	UNIT
V _(ESD)	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001 ⁽¹⁾	±2000	V
		Charged-device model (CDM), per ANSI/ESDA/JEDEC JS-002 ⁽²⁾	±500	

- (1) JEDEC document JEP155 states that 500V HBM allows safe manufacturing with a standard ESD control process.
- (2) JEDEC document JEP157 states that 250V CDM allows safe manufacturing with a standard ESD control process.

5.3 Recommended Operating Conditions

T_{amb} = −40°C to 125°C; unless otherwise specified

			MIN	TYP	MAX	UNIT
VDD1	Supply voltage 1		0.65		3.6	V
VDD2	Supply voltage 2		1.65		3.6	V
IDD (VDD2)	Supply Current on VDD2	VDD1 = 3.6; VDD2 = 3.6; SC0-7 and SD0-7 is not connected; RESET = VDD1; A0=A1=SCL; continuous register read/write				
		SCL = 0kHz		4	16	μA
		SCL = 100kHz		11	24	μA
		SCL = 1000kHz		56	150	μA
IDD (VDD1)	Supply Current on VDD1	VDD1 = 3.6; VDD2 = 3.6; SC0-7 and SD0-7 is not connected; RESET = VDD1; A0=A1=SCL; continuous register read/write				
		SCL = 0kHz	−5	0.11	+5	μA
		SCL = 100kHz		8	15	μA
		SCL = 1000kHz		58	100	μA
VPOR	Power-On Reset Voltage			1.2	1.5	V
T _A	Operating free-air temperature		−40		125	°C

5.4 Thermal Information

THERMAL METRIC ⁽¹⁾		TCA984x		UNIT
		PW (TSSOP)	RUM (WQFN)	
		16 PINS	16 PINS	
R _{θJA}	Junction-to-ambient thermal resistance	113.3	68.3	°C/W
R _{θJC(top)}	Junction-to-case (top) thermal resistance	53.1	54.3	°C/W
R _{θJB}	Junction-to-board thermal resistance	71.2	43.9	°C/W

THERMAL METRIC ⁽¹⁾		TCA984x		UNIT
		PW (TSSOP)	RUM (WQFN)	
		16 PINS	16 PINS	
ψ_{JT}	Junction-to-top characterization parameter	9.8	7.6	°C/W
ψ_{JB}	Junction-to-board characterization parameter	70.8	44	°C/W
$R_{\theta JC(bot)}$	Junction-to-case (bottom) thermal resistance	N/A	28.5	°C/W

- (1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application note.

5.5 Electrical Characteristics (Global)

$T_A = 25^\circ\text{C}$ (unless otherwise noted)

PARAMETER		TEST CONDITIONS	T _A	MIN	TYP	MAX	UNIT
Recommended Supply Sequencing and Ramp Rates							
(dV/dt) _f	fall rate of change of voltage		−40°C to +125°C	0.1		2000	ms
(dV/dt) _r	rise rate of change of voltage		−40°C to +125°C	0.1		2000	ms
t _{d(rst)}	reset delay time		−40°C to +125°C	10			us
ΔV _{DD(gl)}	glitch supply voltage difference		−40°C to +125°C			1	V
t _{w(gl)VDD}	supply voltage glitch pulse width		−40°C to +125°C			10	us
V _{POR(trip)}	power-on reset trip voltage	Falling VDD2	−40°C to +125°C	0.7			V
		Rising VDD2	−40°C to +125°C			1.5	V
SCL/SDA							
V _{IH}	Logic voltage high		−40°C to +125°C	0.7V _{DD1}		3.6	V
V _{IL}	Logic voltage low		−40°C to +125°C	−0.5	+0.3V _{D_{D1}}		V
I _{OL}	LOW-level output current	V _{OL} = 0.4V	−40°C to +125°C	20			mA
I _{IL}	Input leakage current	VI = VDD or 0	−40°C to +125°C	−1		1	uA
C _{IN}	Logic input capacitance	VI = VSS; all channels disabled	−40°C to +125°C		10	12	pF
SEL Inputs: A0A1, RESET							
V _{IH}	Logic voltage high		−40°C to +125°C	0.7V _{DD1}		3.6	V
V _{IL}	Logic voltage low		−40°C to +125°C	−0.5	+0.3V _{D_{D1}}		V
I _{IL}	Input leakage current	VI = VDD or 0	−40°C to +125°C	−1		1	μA
C _{IN}	Logic input capacitance	VI = VSS; all channels disabled	−40°C to +125°C		2	4	pF
Pass Gate							
R _{ON}	ON-state resistance	VDD1 = 0.8V; VDD2 ≥ 1.65V; Vi(sw) = 0.16V; IO = 3mA	−40°C to +125°C		10	24	Ω
		VDD1 = 0.65V; VDD2 ≥ 1.65V; Vi(sw) = 0.16V; IO = 3mA	−40°C to +125°C		10	24	Ω
		VDD1 = 1.2V; VDD2 ≥ 1.8V; Vi(sw) = 0.24V; IO = 6mA	−40°C to +125°C		7	18	Ω
		VDD1 > 2V; VDD2 ≥ 2.5V; Vi(sw) = 0.4V; IO = 20mA	−40°C to +125°C		5	12	Ω
I _o (sw)	Switch Output Current	VDD2 = 1.65V to 3.6V; Vi(sw) = VDD1 to 3.6V; Vo(sw) = VDD1 to 3.6V	−40°C to +125°C	0		100	μA
IL	Leakage current	VI = VDD or GND	−40°C to +125°C	−1		+1.5	μA
COFF	Input/Ouput Capacitance	VI = GND; all switches disables	−40°C to +125°C		3	5	pF

5.6 I²C Interface Timing Requirements

over recommended operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
STANDARD MODE					
f_{scl}	I ² C clock frequency		0	100	kHz
t_{sch}	I ² C clock high time		4		us
t_{scl}	I ² C clock low time		4.7		us
t_{sp}	I ² C spike time		50		ns
t_{sds}	I ² C serial-data setup time		250		ns
t_{sdh}	I ² C serial-data hold time		0 ⁽¹⁾		us
t_{icr}	I ² C input rise time			1000	ns

5.6 I²C Interface Timing Requirements (continued)

over recommended operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
t _{icf}	I ² C input fall time			300	ns
t _{ocf}	I ² C output (SDn) fall time (10pF to 400pF bus)			300	ns
t _{buf}	I ² C bus free time between stop and start		4.7		µs
t _{sts}	I ² C start or repeated start condition setup		4.7		µs
t _{sth}	I ² C start or repeated start condition hold		4		µs
t _{sps}	I ² C stop condition setup		4		µs
t _{vdL(Data)}	Valid-data time (high to low) ⁽²⁾	SCL low to SDA output low valid		1	µs
t _{vdH(Data)}	Valid-data time (low to high) ⁽²⁾	SCL low to SDA output high valid		0.6	µs
t _{vd(ack)}	Valid-data time of ACK condition	ACK signal from SCL low to SDA output low		1	µs
C _b	I ² C bus capacitive load			400	pF
FAST MODE					
f _{scl}	I ² C clock frequency		0	400	kHz
t _{sch}	I ² C clock high time		0.6		µs
t _{scl}	I ² C clock low time		1.3		µs
t _{sp}	I ² C spike time		50		ns
t _{sds}	I ² C serial-data setup time		100		ns
t _{sdh}	I ² C serial-data hold time		0 ⁽¹⁾		µs
t _{icr}	I ² C input rise time		20 + 0.1C _b ⁽³⁾	300	ns
t _{icf}	I ² C input fall time		20 + 0.1C _b ⁽³⁾	300	ns
t _{ocf}	I ² C output (SDn) fall time (10pF to 400pF bus)		20 + 0.1C _b ⁽³⁾	300	ns
t _{buf}	I ² C bus free time between stop and start		1.3		µs
t _{sts}	I ² C start or repeated start condition setup		0.6		µs
t _{sth}	I ² C start or repeated start condition hold		0.6		µs
t _{sps}	I ² C stop condition setup		0.6		µs
t _{vdL(Data)}	Valid-data time (high to low) ⁽²⁾	SCL low to SDA output low valid		1	µs
t _{vdH(Data)}	Valid-data time (low to high) ⁽²⁾	SCL low to SDA output high valid		0.6	µs
t _{vd(ack)}	Valid-data time of ACK condition	ACK signal from SCL low to SDA output low		1	µs
C _b	I ² C bus capacitive load			400	pF
FAST MODE PLUS					
f _{scl}	I ² C clock frequency	I ² C clock frequency	0	1000	kHz
t _{sch}	I ² C clock high time	I ² C clock high time	0.26		µs
t _{scl}	I ² C clock low time	I ² C clock low time	0.5		µs
t _{sp}	I ² C spike time	I ² C spike time		50	ns
t _{sds}	I ² C serial-data setup time	I ² C serial-data setup time	100		ns
t _{sdh}	I ² C serial-data hold time	I ² C serial-data hold time	0 ⁽¹⁾		µs
t _{icr}	I ² C input rise time	I ² C input rise time		120	ns
t _{icf}	I ² C input fall time	I ² C input fall time	20x (VDD / 5.5V) ⁽³⁾	120	ns
t _{buf}	I ² C bus free time between stop and start	I ² C bus free time between stop and start	0.5		µs
t _{sts}	I ² C start or repeated start condition setup	I ² C start or repeated start condition setup	0.26		µs
t _{sth}	I ² C start or repeated start condition hold	I ² C start or repeated start condition hold	0.26		µs
t _{sps}	I ² C stop condition setup	I ² C stop condition setup	0.6		µs
t _{vdL(Data)}	Valid-data time (high to low) ⁽²⁾	SCL low to SDA output low valid		0.45	µs
t _{vdH(Data)}	Valid-data time (low to high) ⁽²⁾	SCL low to SDA output high valid		0.45	µs
t _{vd(ack)}	Valid-data time of ACK condition	ACK signal from SCL low to SDA output low		0.45	µs

5.6 I²C Interface Timing Requirements (continued)

over recommended operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
C _b	I ² C bus capacitive load	I ² C bus capacitive load		550	pF

- (1) A device internally must provide a hold time of at least 300ns for the SDA signal (referred to the V_{IH} min of the SCL signal), to bridge the undefined region of the falling edge of SCL.
- (2) Data taken using a 1kΩ pullup resistor and 50pF load
- (3) C_b = total bus capacitance of one bus line in pF

5.7 Reset Timing Requirements

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		MIN	MAX	UNIT
t _{wrs(L)}	Low-level reset time	100		ns
t _{REC(STA)}	Recovery time from $\overline{\text{RESET}}$ to start	0		ns

5.8 Switching Characteristics

over recommended operating free-air temperature range, C_L ≤ 100pF (unless otherwise noted)

PARAMETER			FROM (INPUT)	TO (OUTPUT)	MIN	MAX	UNIT
t _{pd} ⁽¹⁾	Propagation delay time	R _{ON} = 20 Ω, C _L = 50pF	SDA or SCL	SDn or SCn		1	ns
t _{rst} ⁽²⁾	$\overline{\text{RESET}}$ time (SDA clear)		$\overline{\text{RESET}}$	SDA	500		ns

- (1) The propagation delay is the calculated RC time constant of the typical ON-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).
- (2) t_{rst} is the propagation delay measured from the time the $\overline{\text{RESET}}$ pin is first asserted low to the time the SDA pin is asserted high, signaling a stop condition. t_{rst} must be a minimum of t_{WL}.

6 Typical Characteristics

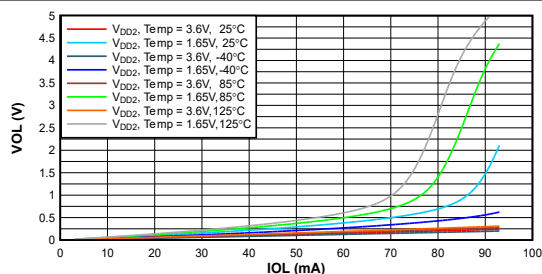


Figure 6-1. SDA Output Low Voltage (V_{OL}) vs Load Current (I_{OL}) at V_{DD2} Levels = 3.6V, 1.65V and T_A = -40°C, 25°C, 85°C, 125°C

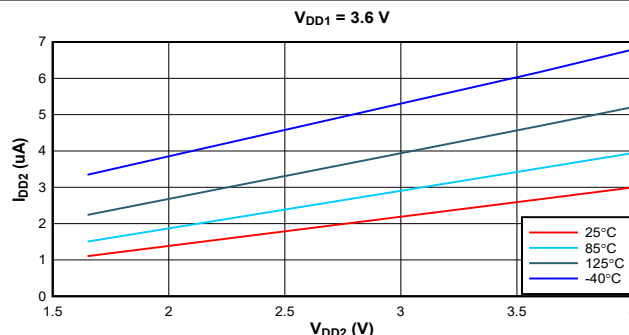


Figure 6-2. Standby Current (I_{DD}) vs Supply Voltage (V_{DD2}) at Four Temperature Points

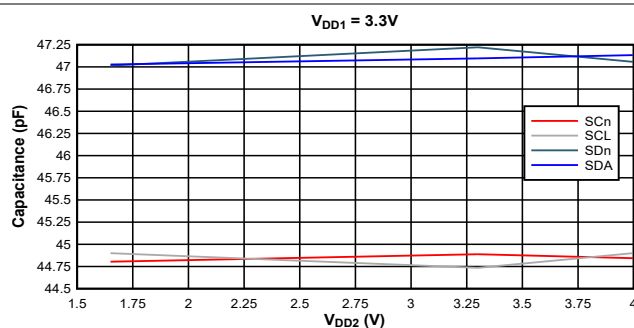


Figure 6-3. Target Channel (SCn/SDn) Capacitance ($C_{IO(OFF)}$) vs Supply Voltage (V_{DD2}) at 25°C

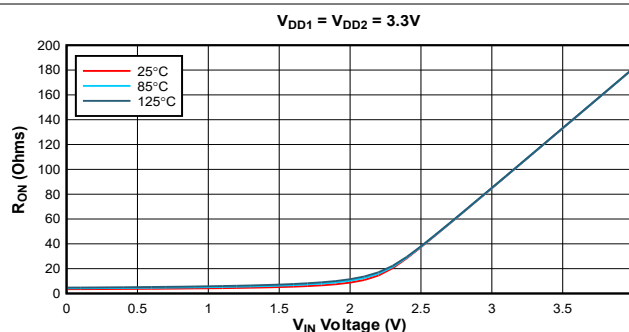
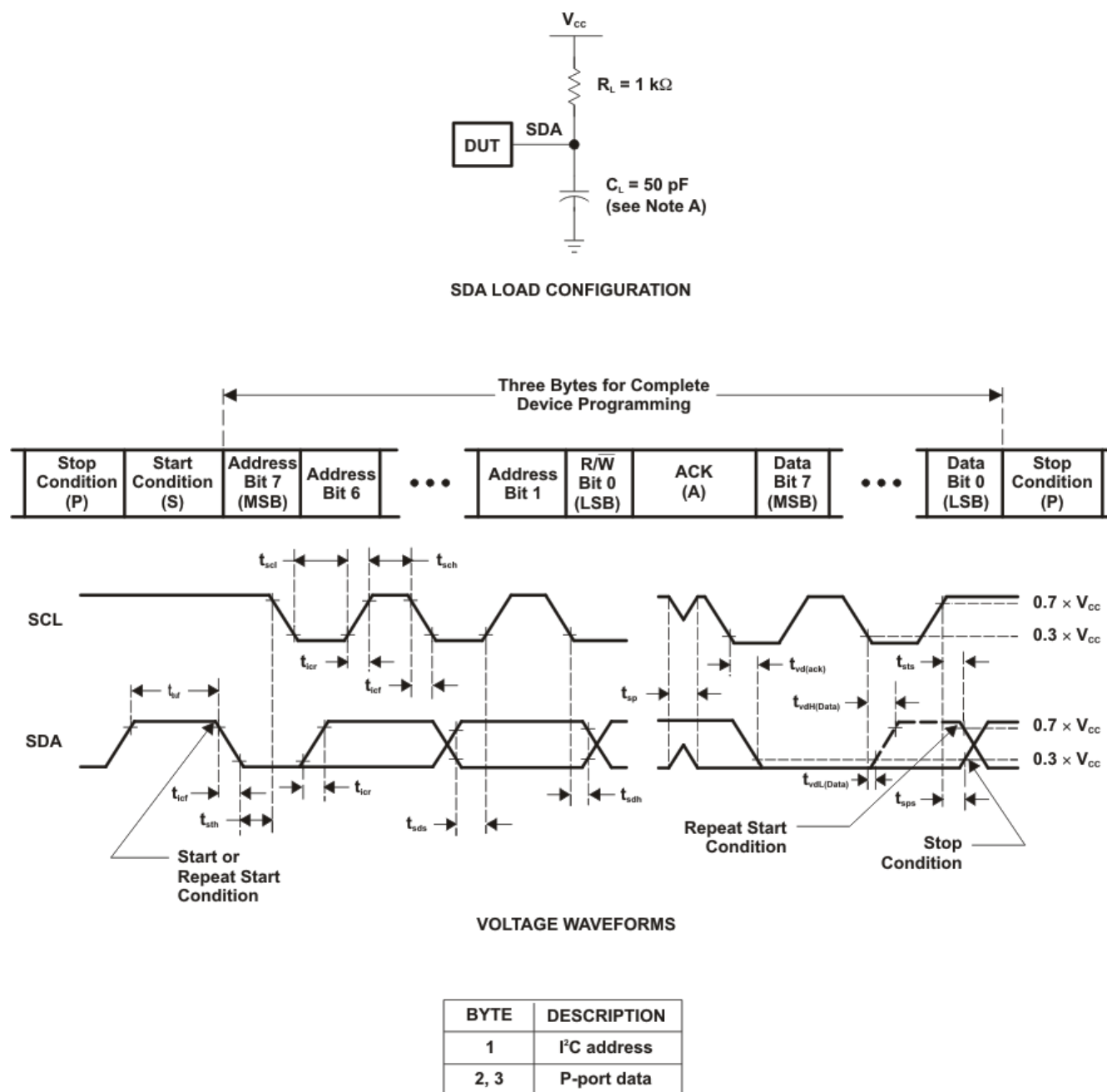


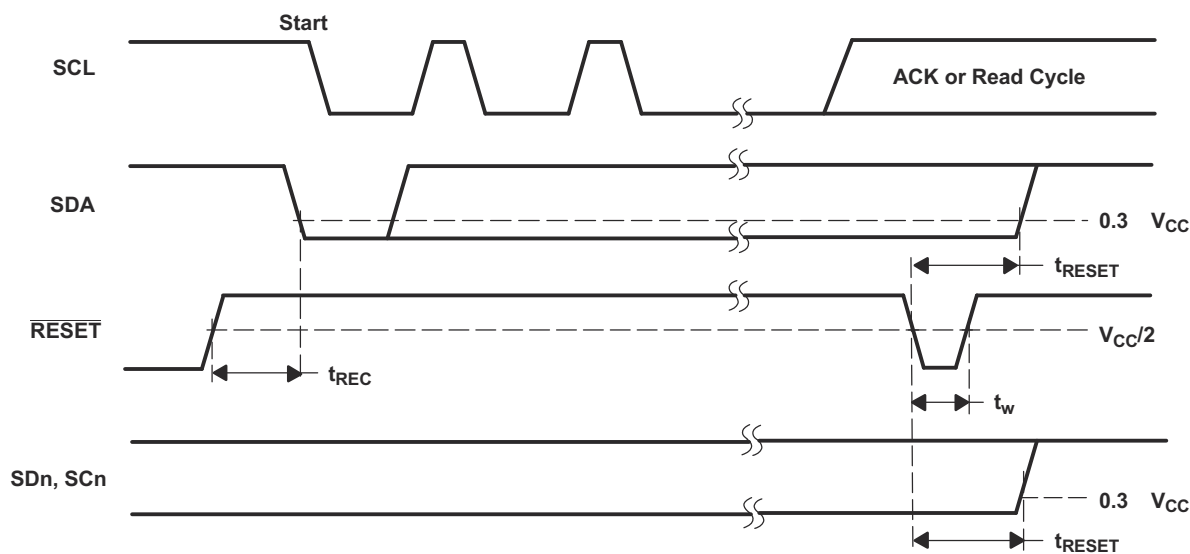
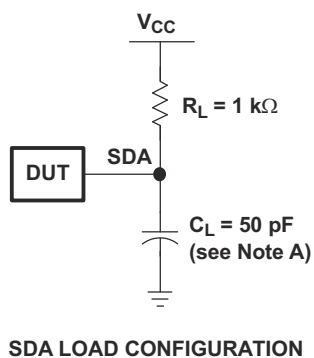
Figure 6-4. On-Resistance (R_{ON}) vs Input Voltage at Three Temperature Points

7 Parameter Measurement Information



- A. C_L includes probe and jig capacitance.
- B. All inputs are supplied by generators having the following characteristics: $PRR \leq 10\text{MHz}$, $Z_O = 50\Omega$, $t_r/t_f \leq 30\text{ns}$.
- C. Not all parameters and waveforms are applicable to all devices.

Figure 7-1. I²C Load Circuit and Voltage Waveforms



- A. C_L includes probe and jig capacitance.
- B. All inputs are supplied by generators having the following characteristics: $PRR \leq 10\text{ MHz}$, $Z_O = 50\Omega$, $t_r/t_f \leq 30\text{ ns}$.
- C. I/Os are configured as inputs.
- D. Not all parameters and waveforms are applicable to all devices.

Figure 7-2. Reset Load Circuit and Voltage Waveforms

8 Detailed Description

8.1 Overview

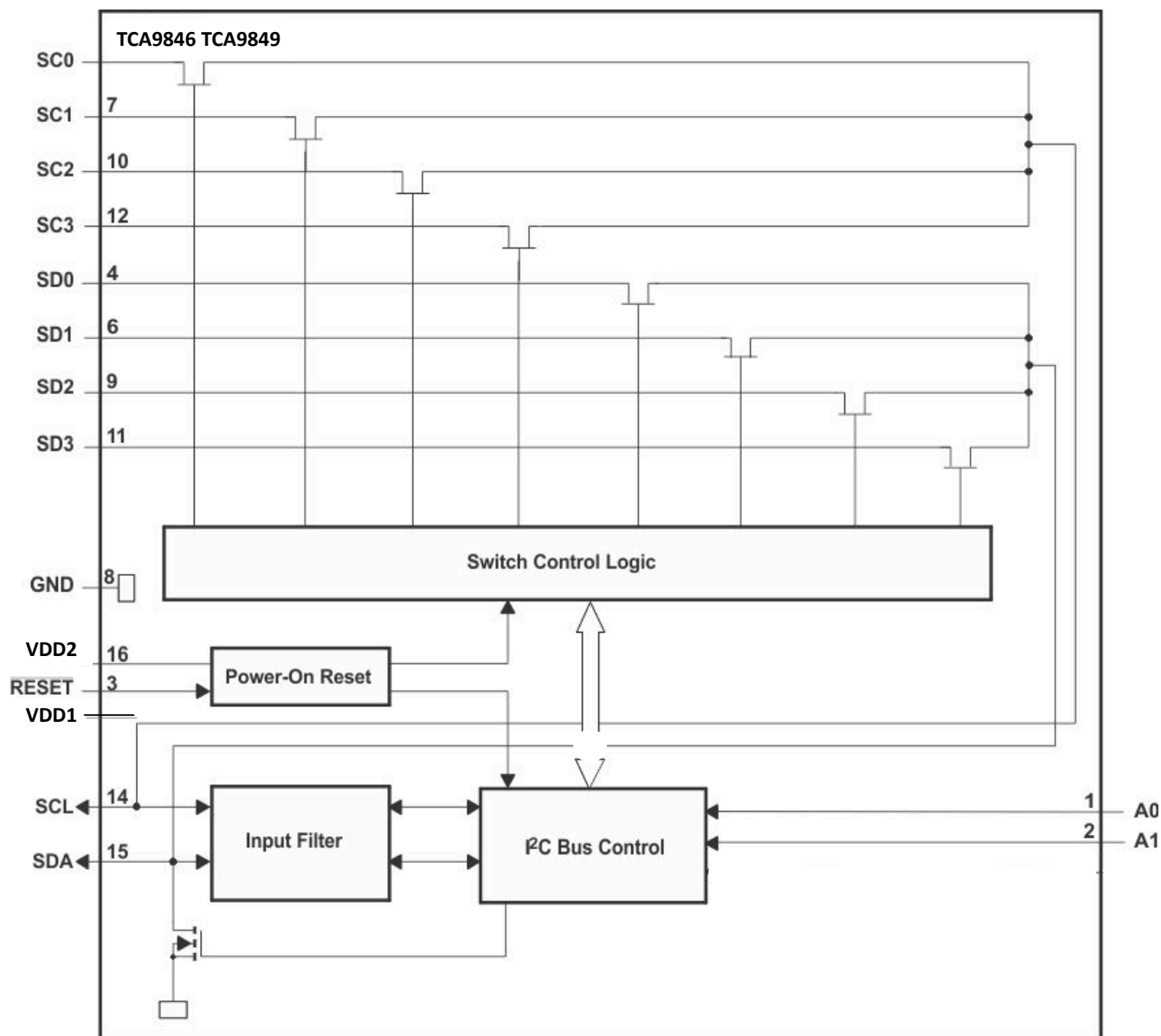
The TCA9849 is a 4-channel, bidirectional translating I2C multiplexer. The controller SCL/SDA signal pair is directed to four channels of target devices, SC0/SD0-SC3/SD3. Any individual downstream channel can be selected as per the control register setting.

The device offers an active-low $\overline{\text{RESET}}$ input which resets the state machine and allows the TCA9849 to recover if one of the downstream I2C buses get stuck in a low state. The state machine of the device can also be reset by cycling the power supply, VCC, also known as a power-on reset (POR). Both the $\overline{\text{RESET}}$ function and a POR cause all channels to be deselected.

The connections of the I2C data path are controlled by the same I2C controller device that is switched to communicate with multiple I2C targets. After the successful acknowledgment of the target's address (hardware selectable by A0 and A1 pins), a single 8-bit control register is written to or read from to determine the selected channels.

The TCA9849 can also be used for voltage translation, allowing the use of different bus voltages on each SCn/SDn pair such that 0.65V, 0.8V, 1.2V, or 1.8V parts can communicate with 3.3V parts. This is achieved by using external pull-up resistors to pull the bus up to the desired voltage for the controller and each target channel.

8.2 Functional Block Diagram



8.3 Feature Description

The TCA9849 is an 4-channel, bidirectional translating multiplexer for I²C buses that supports Standard-Mode (100kHz), Fast-Mode (400kHz), and Fast-Mode-Plus (1Mhz) operation. The TCA9849 features I²C control using a single 8-bit control register in which each bit controls the enabling and disabling of one of the corresponding 4 switch channels for I²C data flow. Depending on the application, voltage translation of the I²C bus can also be achieved using the TCA9849 to allow 0.65V, 0.8V, 1.2V, or 1.8V parts to communicate with 3.3V parts.

Additionally, in the event that communication on the I²C bus enters a fault state, the TCA9849 can be reset to resume normal operation using the RESET pin feature or by a power-on reset which results from cycling power to the device.

8.4 Device Functional Modes

8.4.1 RESET Input

The RESET input is an active-low signal that can be used to recover from a bus-fault condition. When this signal is asserted low for a minimum of t_{WL} , the TCA9849 resets its registers and I²C state machine and deselects all channels. The RESET input must be connected to V_{CC} through a pull-up resistor.

8.4.2 Power-On Reset

When power is applied to the VCC(V_{DD2}) pin, an internal power-on reset holds the TCA9849 in a reset condition until V_{CC} (V_{DD2}) has reached V_{PORR}. At this point, the reset condition is released, and the TCA9849 registers and I²C state machine are initialized to the default states, all zeroes, causing all the channels to be deselected. Thereafter, V_{CC} must be lowered below V_{PORF} to reset the device.

8.5 Programming

8.5.1 I²C Interface

The TCA9849 has a standard bidirectional I²C interface that is controlled by a controller device to be configured or read the status of this device. Each target on the I²C bus has a specific device address to differentiate between other target devices that are on the same I²C bus. Many target devices require configuration upon startup to set the behavior of the device. This is typically done when the controller accesses internal register maps of the target, which have unique register addresses. A device can have one or multiple registers where data is stored, written, or read.

The physical I²C interface consists of the serial clock (SCL) and serial data (SDA) lines. Both SDA and SCL lines must be connected to V_{CC} through a pull-up resistor. The size of the pull-up resistor is determined by the amount of capacitance on the I²C lines. (For further details, see the [I²C Pull-up Resistor Calculation](#) application note. Data transfer can be initiated only when the bus is idle. A bus is considered idle if both SDA and SCL lines are high after a STOP condition (See [Figure 8-1](#) and [Figure 8-2](#)).

The following is the general procedure for a controller to access a target device:

1. If a controller wants to send data to a target:
 - Controller-transmitter sends a START condition and addresses the target-receiver.
 - Controller-transmitter sends data to target-receiver.
 - Controller-transmitter terminates the transfer with a STOP condition.
2. If a controller wants to receive or read data from a target:
 - Controller-receiver sends a START condition and addresses the target-transmitter.
 - Controller-receiver sends the requested register to read to target-transmitter.
 - Controller-receiver receives data from the target-transmitter.
 - Controller-receiver terminates the transfer with a STOP condition.

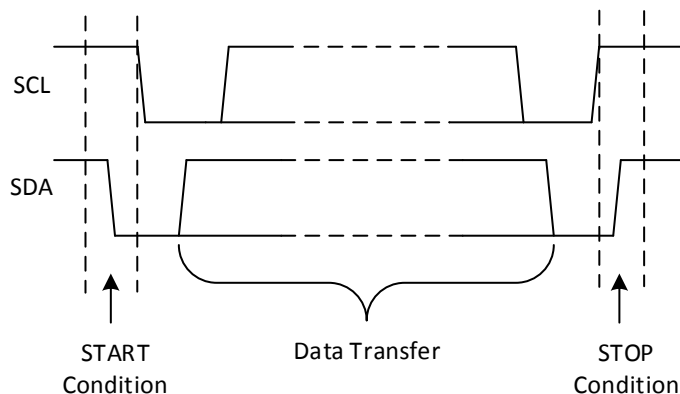


Figure 8-1. Definition of Start and Stop Conditions

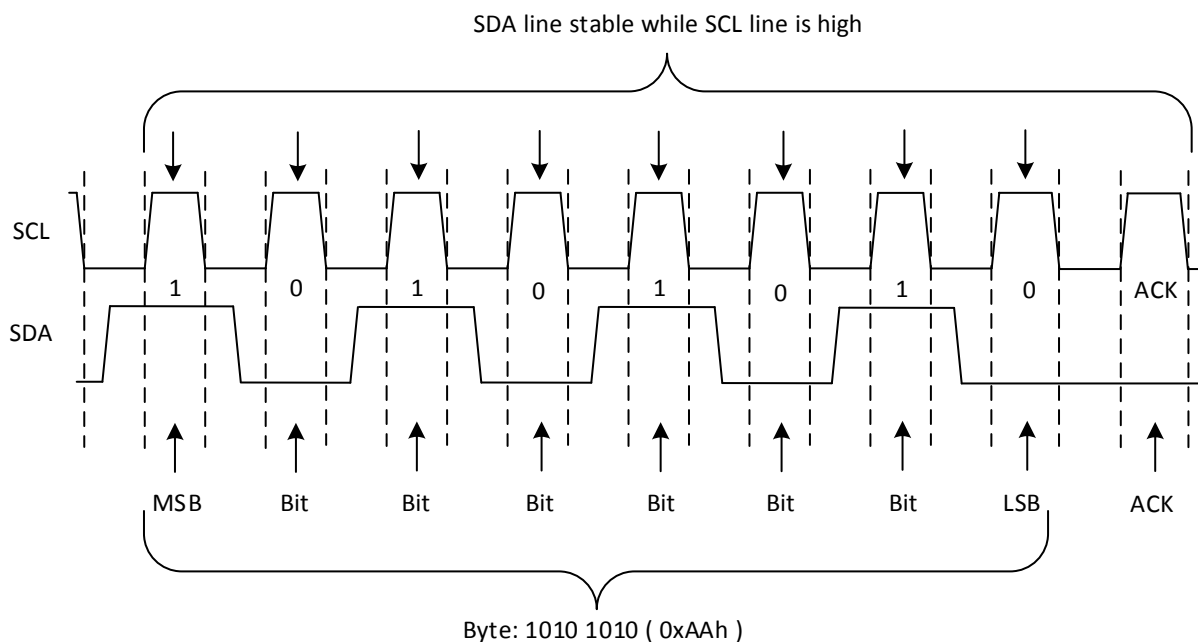


Figure 8-2. Bit Transfer

8.5.2 Device Address

The last bit of the target address defines the operation (read or write) to be performed. When it is high (1), a read is selected, while a low (0) selects a write operation.

For a read and write routine in software world for TCA984x, the actual address is 7 bit. For Example, 0xE2 = Write Operation on 0x71I2C address (Address = 0x71 and then we shift left and add last bit for read/write, which has the I2C bus address write of 0xE2).

Table 8-1 shows the TCA9849 address reference.

Table 8-1. Address Reference

INPUTS		I ² C BUS TARGETADDRESS
A1	A0	
L	SCL	0xE0h (hexadecimal)
L	L	0xE2h (hexadecimal)
L	SDA	0xE4h (hexadecimal)
L:	H	0xE6h (hexadecimal)
H	SCL	0xE8h (hexadecimal)
H	L	0xEA h (hexadecimal)
H	SDA	0xECh (hexadecimal)
H	H	0xEEh (hexadecimal)
SCL	SCL	0xB0h (hexadecimal)
SCL	L	0xB2h (hexadecimal)
SCL	SDA	0xB4h (hexadecimal)
SCL	H	0xB6h (hexadecimal)
SDA	SCL	0xB8h (hexadecimal)
SDA	L	0xBAh (hexadecimal)
SDA	SDA	0xBC h (hexadecimal)
SDA	1	0xBEh (hexadecimal)

8.5.3 Bus Transactions

Data must be sent to and received from the target devices, and this is accomplished by reading from or writing to registers in the target device.

Registers are locations in the memory of the target which contain information; either the configuration information or some sampled data to send back to the controller. The controller must write information to these registers to instruct the target device to perform a task.

Designs commonly have registers in I²C targets, note that not all target devices have registers. Some devices are simple and contain only one register, which can be written to directly by sending the register data immediately after the target address, instead of addressing a register. The TCA9849 is example of a single-register device, which is controlled via I²C commands. Since the device has one bit to enable or disable a channel, there is only one register needed, and the controller merely writes the register data after the target address, skipping the register number.

8.5.3.1 Writes

To write on the I²C bus, the controller sends a START condition on the bus with the address of the target, as well as the last bit (the R/ $\bar{W}$ bit) set to 0, which signifies a write. The target acknowledges, letting the controller know it is ready. After this, the controller starts sending the control register data to the target until the controller has sent all the data necessary (which is sometimes only a single byte), and the controller terminates the transmission with a STOP condition.

There is no limit to the number of bytes sent, but the last byte sent is what is in the register.

Figure 8-3 shows an example of writing a single byte to a target register.

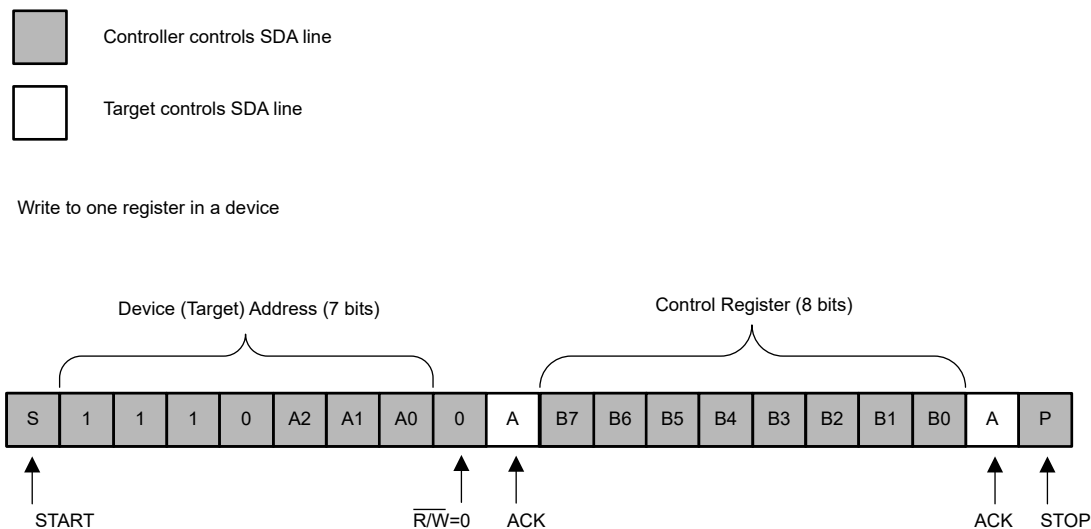


Figure 8-3. Write to Register

8.5.3.2 Reads

Reading from a target is very similar to writing, but the controller sends a START condition, followed by the target address with the R/ $\bar{W}$ bit set to 1 (signifying a read). The target acknowledges the read request, and the controller releases the SDA bus but continues supplying the clock to the target. During this part of the transaction, the controller becomes the controller-receiver, and the target becomes the target-transmitter.

The controller continues to send out the clock pulses, but releases the SDA line so that the target can transmit data. At the end of every byte of data, the controller sends an ACK to the target, letting the target know that it is ready for more data. Once the controller has received the number of bytes it is expecting, it sends a NACK, signaling to the target to halt communications and release the bus. The controller follows this up with a STOP condition.

Figure 8-4 shows an example of reading a single byte from a target register.

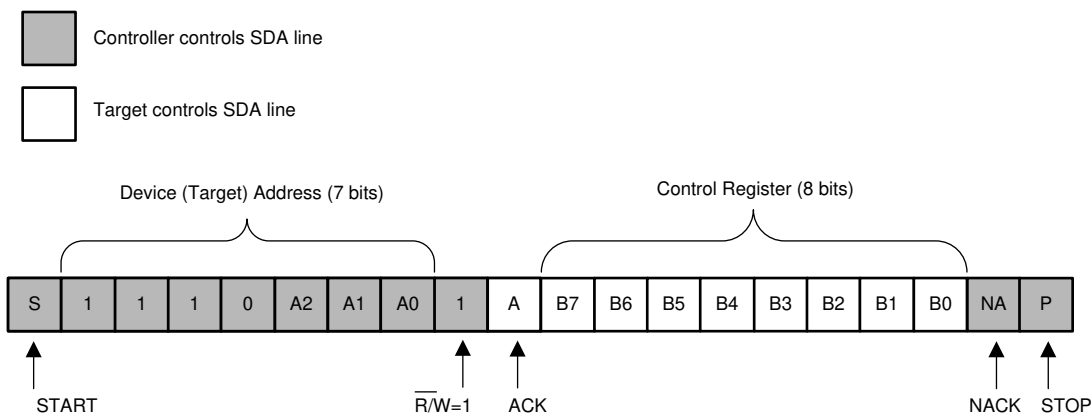


Figure 8-4. Read from Control Register

8.5.4 Control Register

Following the successful acknowledgment of the address byte, the bus controller sends a command byte that is stored in the control register in the TCA9849 (see Figure 8-5). This register can be written and read via the I²C bus. Each bit in the command byte corresponds to a SCn/SDn channel and a high (or 1) selects this channel. Only a single SCn/SDn channel can be selected at a time. When a channel is selected, the channel becomes active after a stop condition has been placed on the I²C bus. This makes sure that all SCn/SDn lines are in a high state when the channel is made active, so that no false conditions are generated at the time of connection. A stop condition always must occur immediately after the acknowledge cycle. If multiple bytes are received by the TCA9849, the last byte received is saved.

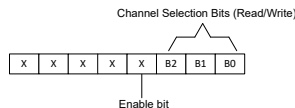


Figure 8-5. Control Register

Table 8-2 shows the TCA9849 Command Byte Definition.

Table 8-2. Command Byte Definition

CONTROL REGISTER BITS ⁽¹⁾								COMMAND
D7	D6	D5	D4	B3	B2	B1	B0	
X	X	X	X	X	0	X	X	No Channel selected
X	X	X	X	X	1	0	0	Channel 0 is selected
X	X	X	X	X	1	0	1	Channel 1 is selected
X	X	X	X	X	1	1	0	Channel 2 is selected
X	X	X	X	X	1	1	1	Channel 3 is selected
0	0	0	0	0	0	0	0	No channel selected, power-up/reset default state

(1) Only one channel can be enabled at a time. The default condition is all zeroes (all channels disabled).

8.5.5 RESET Input

The $\overline{\text{RESET}}$ input is an active-low signal that can be used to recover from a bus-fault condition. When this signal is asserted low for a minimum of t_{WL} , the TCA9849 resets its registers and I²C state machine and deselects all channels. The $\overline{\text{RESET}}$ input must be connected to V_{CC} through a pull-up resistor.

8.5.6 Power-On Reset

When power (from 0V) is applied to V_{DD} , an internal power-on reset holds the TCA9849 in a reset condition until V_{DD} has reached V_{POR} . At that point, the reset condition is released and the TCA9849 registers and I²C state machine initialize to the default states. After that, V_{CC} must be lowered to below V_{POR} and then back up to the operating voltage for a power-reset cycle.

8.5.6.1 Software Reset

The software reset call provides a mechanism to return all devices on the I²C bus to the power-up default state by issuing a specifically formatted I²C command. This operation assumes that the I²C bus is operating correctly and that no device is holding the bus in a latched or “hung” condition. The software reset sequence is defined as the following:

1. The I²C controller issues a START condition.
2. The controller transmits the reserved General Call address '0000 000' with the R/W bit set to 0 (write).
3. A device acknowledges only when the device detects the full General Call address 0000 0000 (00h). If the R/W bit is set to 1 (read), no acknowledge is generated.
4. After the General Call address is acknowledged, the controller transmits a single data byte with the value 06h.
 - a. The device acknowledges only when this data byte is equal to 06h.
 - b. If the data byte is not 06h, or if more than one data byte is transmitted, the device does not acknowledge further.
 - c. When the correct byte has been received and acknowledged, the controller must issue a STOP condition to complete the Software Reset sequence. At this point, the device resets the registers to the power-up default values and becomes ready for subsequent bus transactions after the required bus-free time.
 - d. If a Repeated START condition is issued instead of a STOP, the reset is not performed.
 - e. Any missing acknowledge from the device at any point in this sequence is treated by the controller as a Software Reset Abort. In such a case, the device does not initiate any register reset.

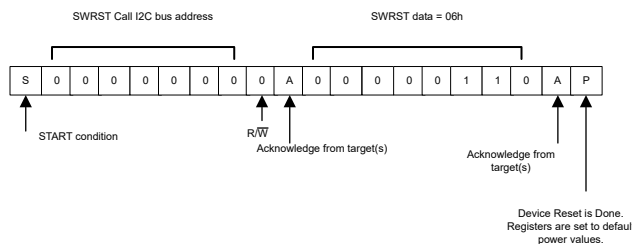


Figure 8-6. Software Reset Sequence

8.5.6.2 Device ID

The Device ID is a 24-bit (3-byte) read-only value containing the following fields:

- 12 bits: manufacturer identifier (unique per manufacturer, for example, TI)
- 9 bits: part number (assigned by the manufacturer)
- 3 bits: die revision (assigned by the manufacturer)

The Device ID is hardwired and accessible using the following procedure:

1. Send a START command.
2. The controller transmits the Reserved Device ID I²C address (1111 1000) with R/W = 0 (write).
3. The controller sends the target device address, with the LSB as “don’t care.” Only the matching device acknowledges.
4. Issue a Repeated START condition.

- a. A STOP command followed by a START command resets the target state machine and the Device ID read cannot be performed. Also, a STOP command or a Re-START command followed by an access to another target device resets the target state machine and the Device ID Read cannot be performed.
5. The controller sends the Reserved Device ID I²C address (1111 1001) with R/W = 1 (read).
6. The device transmits the Device ID in the following order:
 - a. First byte + 4MSBs of second byte: Manufacturer ID (12 bits)
 - b. 4LSBs of second byte + 5MSBs of third byte: Part Identification (9 bits)
 - c. 3LSBs of third byte: Die Revision (3 bits)
7. The controller completes the read by sending a NACK after the last byte, resetting the device internal state machine and then issuing a STOP command.

If the controller sends additional acknowledgments after the third byte, the device restarts the data sequence from the first byte.

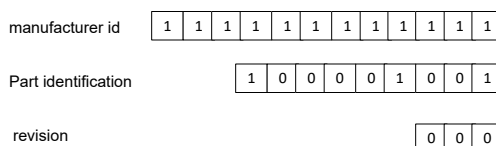
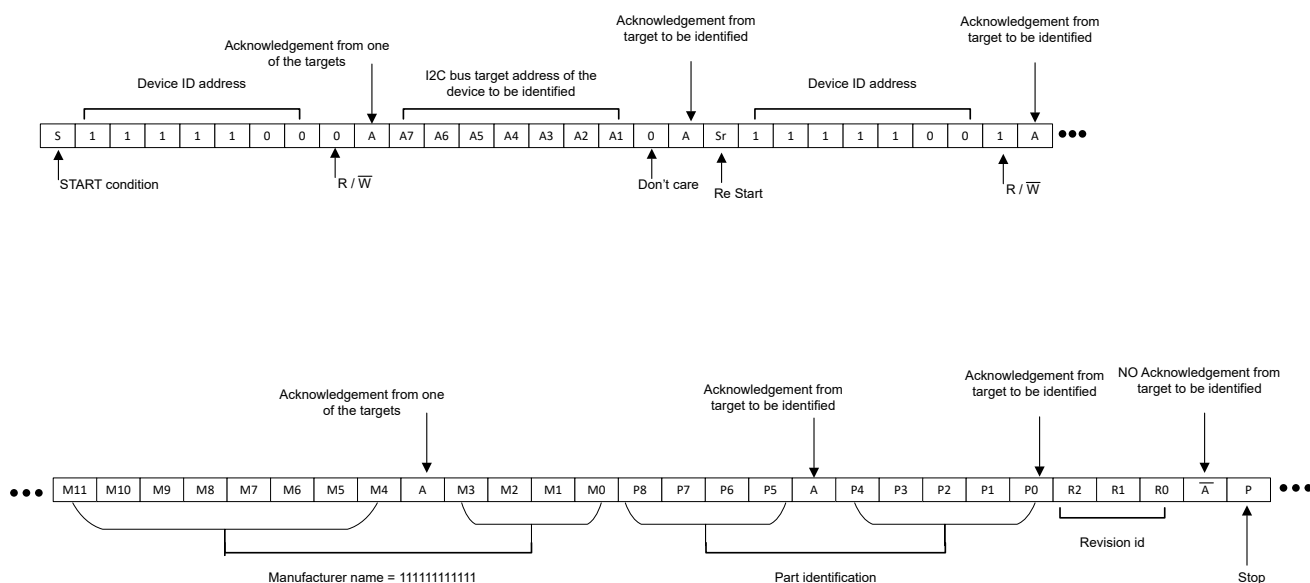


Figure 8-7. Device ID



If more than 3 bytes are read, the target device loops back to the first byte (manufacturer byte) and keeps sending data until the controller generates a 'no acknowledge'.

Figure 8-8. Device ID Sequence

9 Application and Implementation

Note

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes, as well as validating and testing their design implementation to confirm system functionality.

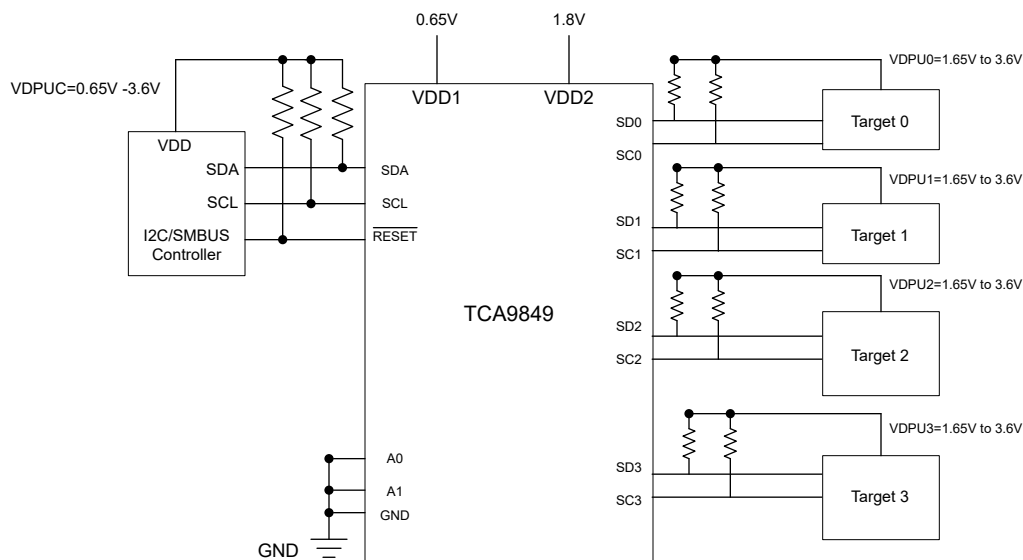
9.1 Application Information

Applications of the TCA9549 contain an I²C (or SMBus) controller device and up to eight I²C target devices. The downstream channels are used to resolve I²C target address conflicts. For example, if four identical digital temperature sensors are needed in the application, one sensor can be connected at each channel: 0-3. When the temperature at a specific location is read, the appropriate channel can be enabled and all other channels switched off, the data can be retrieved, and the I²C controller can move on and read the next channel.

In an application where the I²C bus contains many additional target devices that do not result in I²C target address conflicts, these target devices can be connected to any desired channel to distribute the total bus capacitance across multiple channels. If multiple switches are enabled simultaneously, additional design requirements must be considered (see the [Design Requirements](#) section and [Detailed Design Procedure](#) section).

9.2 Typical Application

Figure 9-1 shows an application in which the TCA9849 can be used.



Pin numbers shown are for the PW package.

Figure 9-1. Typical Application Schematic

9.2.1 Design Requirements

A typical application of the TCA9849 contains one or more data pull-up voltages, V_{DPUX} , one for the controller device (V_{DPUM}) and one for each of the selectable target channels ($V_{DPU0} - V_{DPU3}$). In the event where the controller device and all target devices operate at the same voltage, then $V_{DPUM} = V_{DPUX} = V_{CC}$. In an application where voltage translation is necessary, additional design requirements must be considered to determine an appropriate V_{CC} voltage.

The A0, A1 pins are hardware selectable to control the target address of the TCA9849. These pins can be tied directly to GND or V_{CC} in the application.

If multiple target channels are activated simultaneously in the application, then the total I_{OL} from SCL/SDA to GND on the controller side is the sum of the currents through all pull-up resistors, R_p .

The pass-gate transistors of the TCA9849 are constructed such that the V_{CC} voltage can be used to limit the maximum voltage that is passed from one I²C bus to another.

For the TCA9849 to act as a voltage translator, the V_{pass} voltage must be equal to or lower than the lowest bus voltage.

9.2.2 Detailed Design Procedure

Once all the targets are assigned to the appropriate target channels and bus voltages are identified, the pull-up resistors, R_p , for each of the buses need to be selected appropriately. The minimum pull-up resistance is a function of V_{DPUX} , $V_{OL(max)}$, and I_{OL} as shown in Equation 1:

$$R_{p(min)} = \frac{V_{DPUX} - V_{OL(max)}}{I_{OL}} \quad (1)$$

The maximum pull-up resistance is a function of the maximum rise time, t_r (300ns for fast-mode operation, $f_{SCL} = 400kHz$) and bus capacitance, C_b as shown in Equation 2:

$$R_{p(max)} = \frac{t_r}{0.8473 \times C_b} \quad (2)$$

The maximum bus capacitance for an I²C bus must not exceed 400pF for fast-mode operation. The bus capacitance can be approximated by adding the capacitance of the TCA9849, $C_{iO(OFF)}$, the capacitance of wires, connections and traces, and the capacitance of each individual target on a given channel. If multiple channels are activated simultaneously, each of the targets on all channels contribute to total bus capacitance.

9.2.3 Application Curves

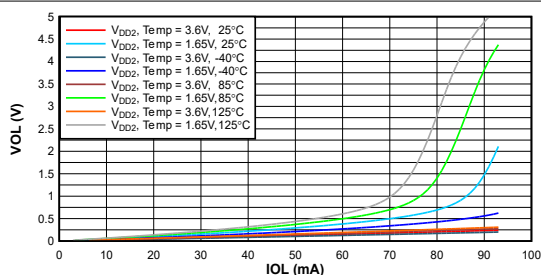


Figure 9-2. SDA Output Low Voltage (V_{OL}) vs Load Current (I_{OL}) at V_{DD2} Levels = 3.6V, 1.65V and $T_A = -40^\circ\text{C}$, 25°C , 85°C , 125°C

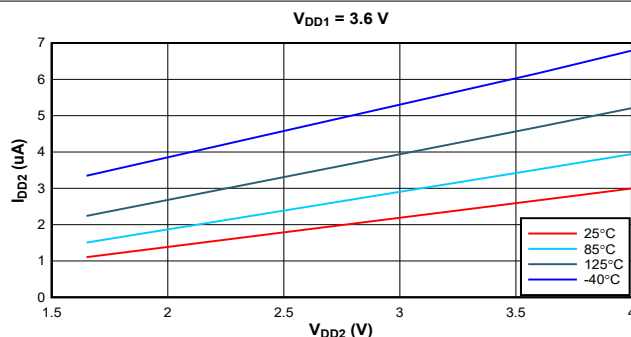
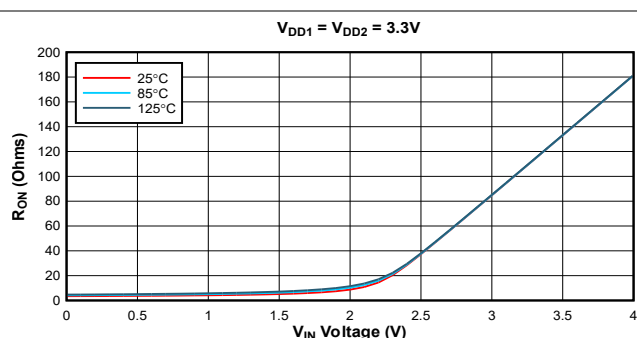
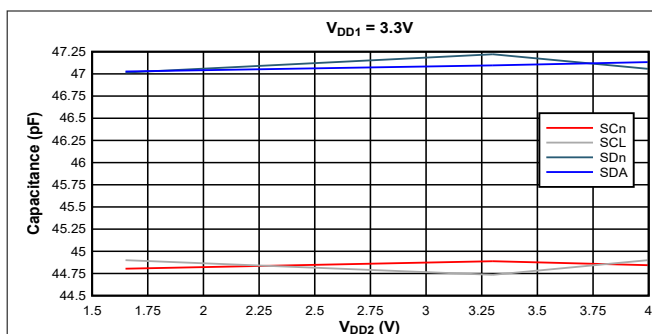


Figure 9-3. Standby Current (I_{DD}) vs Supply Voltage (V_{DD2}) at Four Temperature Points



Glitches in the power supply can also affect the power-on reset performance of this device. The glitch width (V_{CC_GW}) and height (V_{CC_GH}) are dependent on each other. The bypass capacitance, source impedance, and device impedance are factors that affect power-on reset performance. Figure 9-7 and Table 9-1 provide more information on how to measure these specifications.

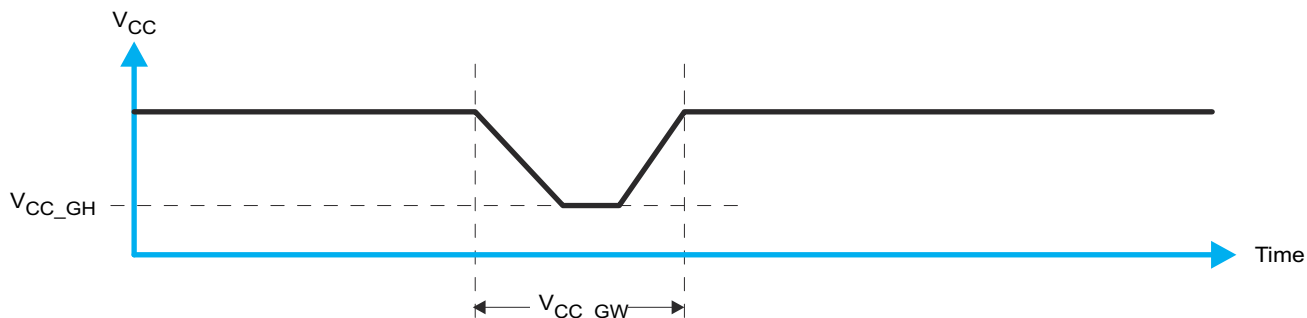


Figure 9-7. Glitch Width and Glitch Height

V_{POR} is critical to the power-on reset. V_{POR} is the voltage level at which the reset condition is released and all the registers and the I²C/SMBus state machine are initialized to the default states. The value of V_{POR} differs based on the V_{CC} (V_{DD2}) being lowered to or from 0. Figure 9-8 and Table 9-1 provide more details on this specification.

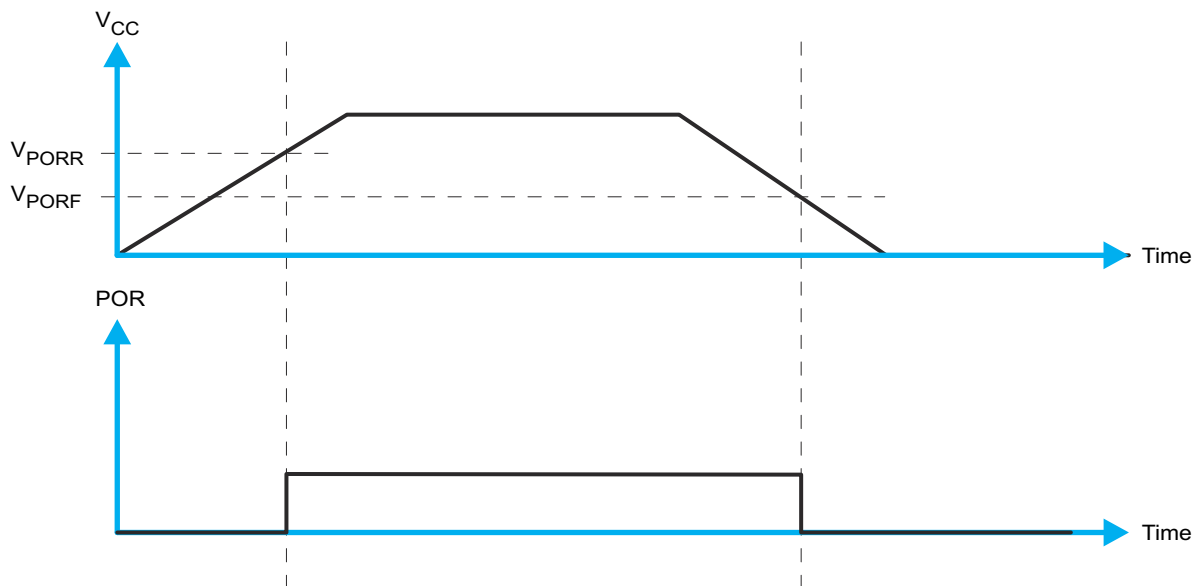


Figure 9-8. V_{POR}

9.4 Layout

9.4.1 Layout Guidelines

For PCB layout of the TCA9548A, common PCB layout practices must be followed but additional concerns related to high-speed data transfer such as matched impedances and differential pairs are not a concern for I²C signal speeds. It is common to have a dedicated ground plane on an inner layer of the board and pins that are connected to ground must have a low-impedance path to the ground plane in the form of wide polygon pours and multiple vias. By-pass and de-coupling capacitors are commonly used to control the voltage on the VCC pin, using a larger capacitor to provide additional power in the event of a short power supply glitch and a smaller capacitor to filter out high-frequency ripple.

In an application where voltage translation is not required, all V_{DPUX} voltages and V_{CC} could be at the same potential and a single copper plane could connect all of pull-up resistors to the appropriate reference voltage. In an application where voltage translation is required, V_{DPU0} and V_{DPU7} , may all be on the same layer of the board with split planes to isolate different voltage potentials.

To reduce the total I²C bus capacitance added by PCB parasitics, data lines (SCn and SDn) must be as short as possible and the widths of the traces must also be minimized (for example, 5-10 mils depending on copper weight).

9.4.2 Layout Example

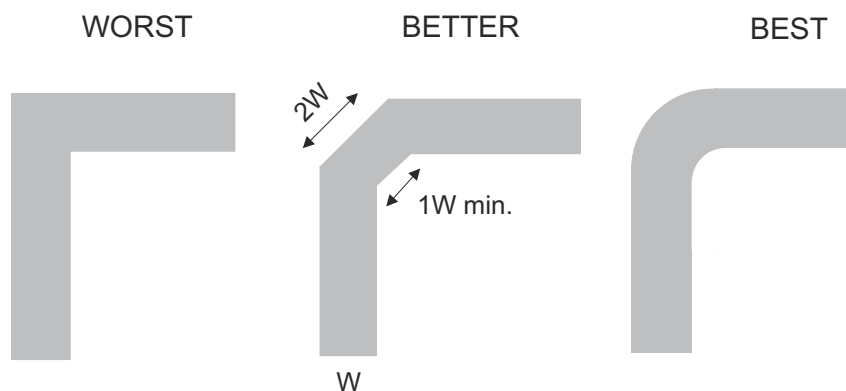


Figure 9-9. Layout Schematic

10 Device and Documentation Support

10.1 Documentation Support

10.1.1 Related Documentation

For related documentation see the following:

- Texas Instruments, [I2C Bus Pull-Up Resistor Calculation](#)
- Texas Instruments, [Maximum Clock Frequency of I2C Bus Using Repeaters](#)
- Texas Instruments, [Introduction to Logic](#)
- Texas Instruments, [Understanding the I2C Bus](#)
- Texas Instruments, [Choosing the Correct I2C Device for New Designs](#)
- Texas Instruments, [TCA9548AEVM User's Guide](#)

10.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on [ti.com](https://www.ti.com). Click on *Notifications* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

10.3 Support Resources

TI E2E™ support forums are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

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10.5 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

10.6 Glossary

[TI Glossary](#) This glossary lists and explains terms, acronyms, and definitions.

11 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision * (May 2026) to Revision A (September 2026)	Page
• Updated data sheet status from <i>Advanced Information to Production Data</i>	1
• Updated <i>Pin Functions</i> table.	3
• Updated <i>Recommended Operating Conditions</i> table.	4
• Added Thermal Information.....	4
• Added <i>Typical Characteristics</i> curves	9
• Updated <i>Device Addresses</i>	15

12 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TCA9849PWR	Active	Production	TSSOP (PW) 16	3000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	TC9849

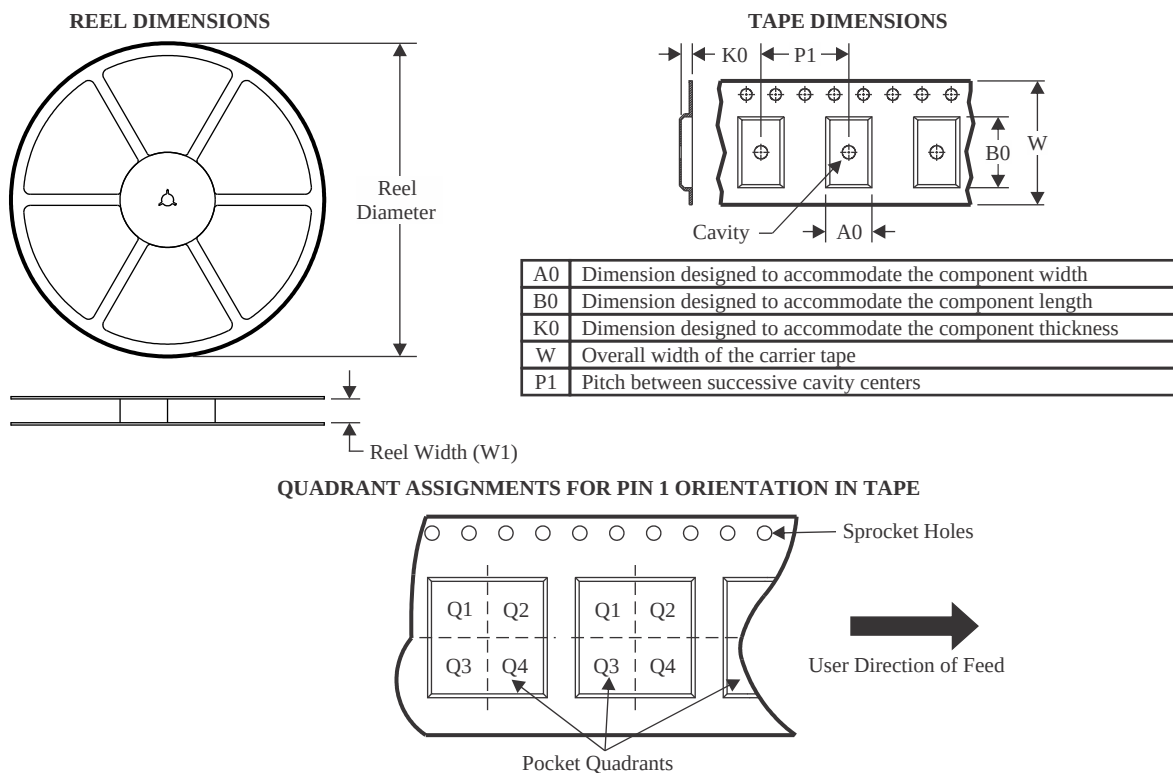
- (1) **Status:** For more details on status, see our [product life cycle](#).
- (2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.
- (3) **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.
- (4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.
- (5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.
- (6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "-" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer:The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

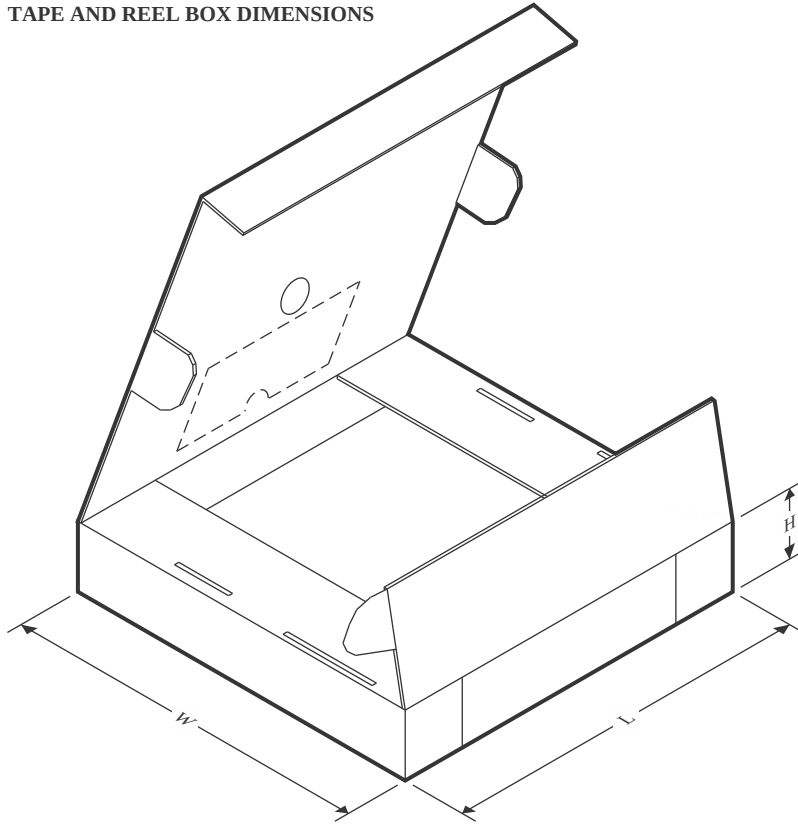
TAPE AND REEL INFORMATION



*All dimensions are nominal

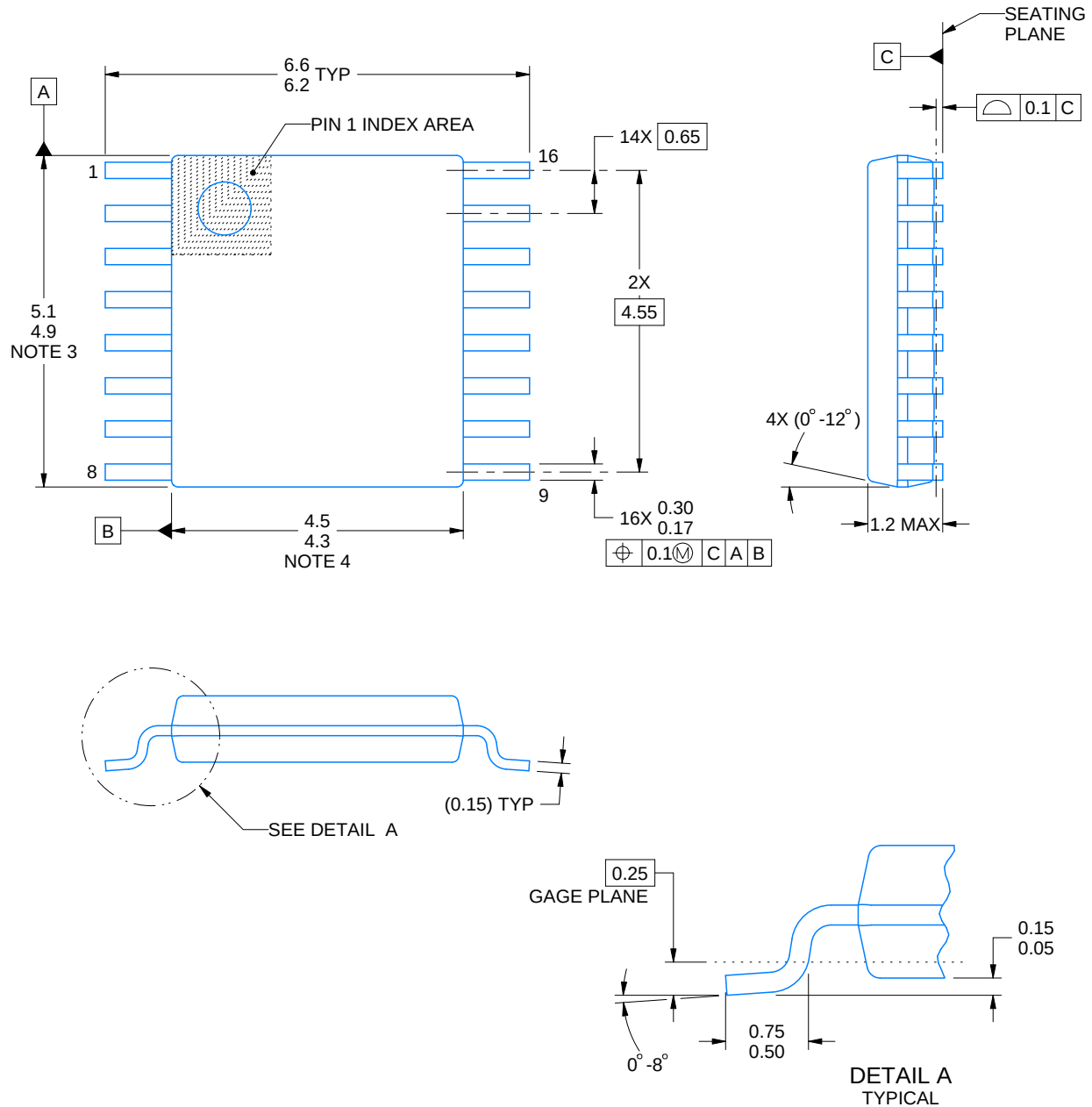
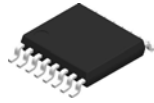
Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TCA9849PWR	TSSOP	PW	16	3000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TCA9849PWR	TSSOP	PW	16	3000	353.0	353.0	32.0



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NOTES:

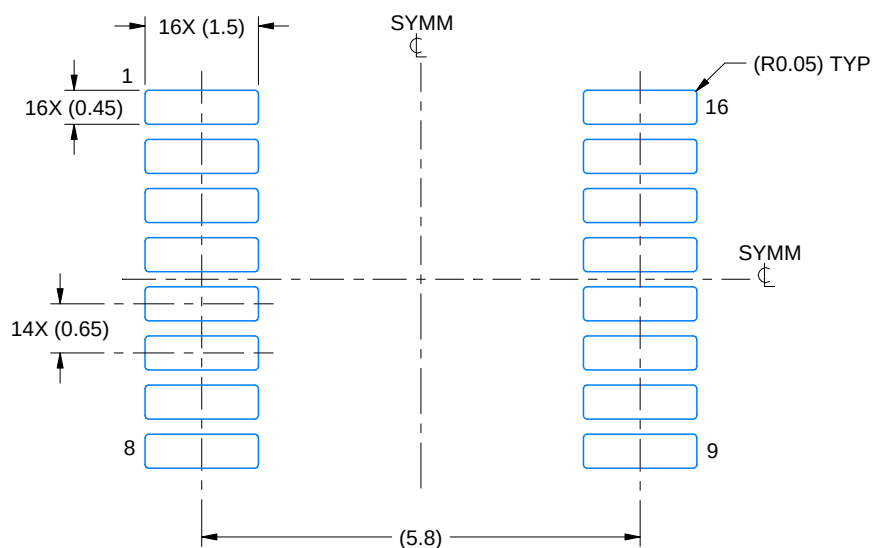
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

EXAMPLE BOARD LAYOUT

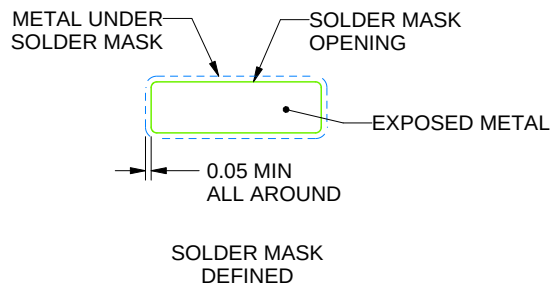
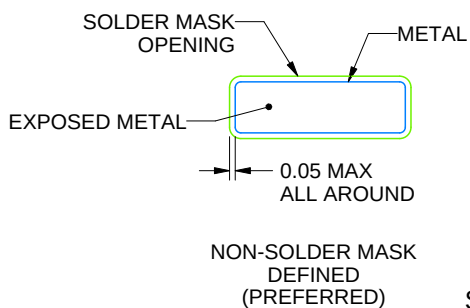
PW0016A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



SOLDER MASK DETAILS

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NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

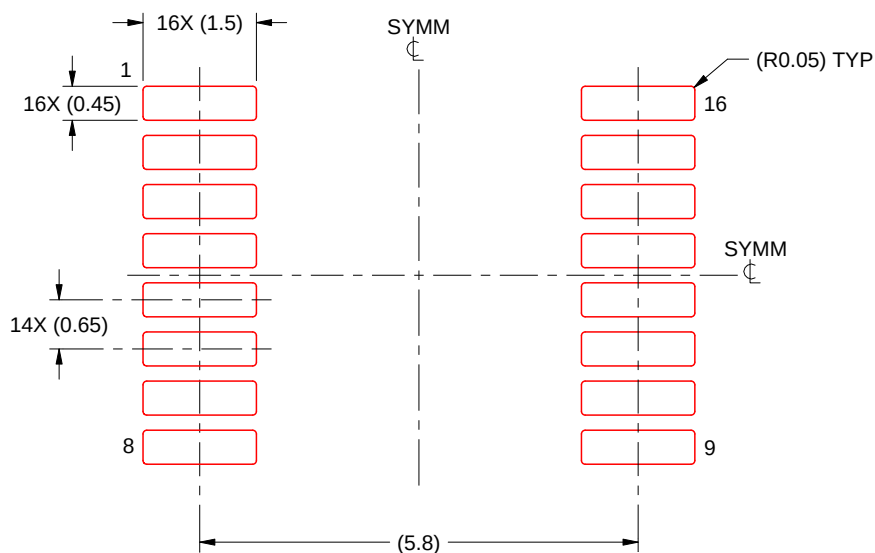
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

PW0016A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



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NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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